

General Features

• $V_{DS} = 50V, I_D = 0.22A$

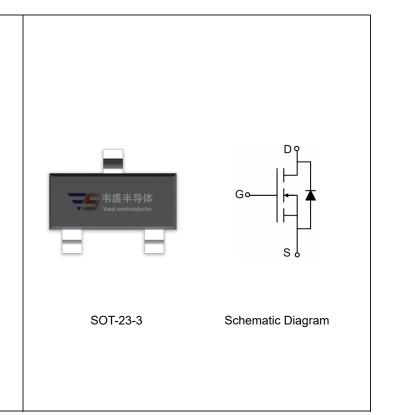
 $R_{DS(ON)} < 3\Omega$ @ $V_{GS}=5V$

 $R_{DS(ON)} < 2\Omega$ @ $V_{GS}=10V$

- Lead free product is acquired
- Surface mount package

Application

- Direct logic-level interface: TTL/CMOS
- Drivers: relays, solenoids, lamps, hammers, display, memories, transistors, etc.
- Battery operated systems
- Solid-state relays



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VSMBSS138-S2	VSMBSS138	SOT-23-3	Ø180mm	8 mm	3000 units

Absolute Maximum Ratings (T_A=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	50	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	0.22	Α
Drain Current-Pulsed (Note 1)	I _{DM}	0.88	Α
Maximum Power Dissipation	P _D	0.35	W
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance,Junction-to-Ambient (Note 2)	$R_{\theta JA}$	350	°C/W
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Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	50	65	-	V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =50V,V _{GS} =0V	-	-	0.5	μΑ	



Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA		
On Characteristics (Note 3)								
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$		1.2	1.6	V		
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =5V, I _D =0.05A	-	1.2	3	Ω		
Dialit-Source Off-State Resistance		V _{GS} =10V, I _D =0.5A	-	1	2	Ω		
Forward Transconductance	g FS	V _{DS} =10V,I _D =0.2A	0.12	-	-	S		
Dynamic Characteristics (Note4)								
Input Capacitance	C _{lss}	V _{DS} =25V,V _{GS} =0V, F=1.0MHz	-	27	-	PF		
Output Capacitance	Coss		-	12	-	PF		
Reverse Transfer Capacitance	C _{rss}	1 -1.000112	-	6	-	PF		
Switching Characteristics (Note 4)								
Turn-on Delay Time	t _{d(on)}		-	2.5	-	nS		
Turn-on Rise Time	t_r V_{DD} =30V, I_D =0.22A		-	6	-	nS		
Turn-Off Delay Time	$t_{d(off)}$	V_{GS} =10 V , R_{GEN} =6 Ω	-	20	-	nS		
Turn-Off Fall Time	t _f		-	7	-	nS		
Total Gate Charge	Q_g	V_{DS} =25V, I_{D} =0.3A, V_{GS} =10V	-	1.7	2.4	nC		
Drain-Source Diode Characteristics								
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =0.22A	-	1	1.3	V		
Diode Forward Current (Note 2)	Is	-	-	-	0.22	Α		

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- **3.** Pulse Test: Pulse Width $\leq 300 \mu s$, Duty Cycle $\leq 2\%$.
- 4. Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics

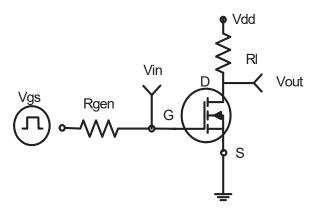


Figure 1:Switching Test Circuit

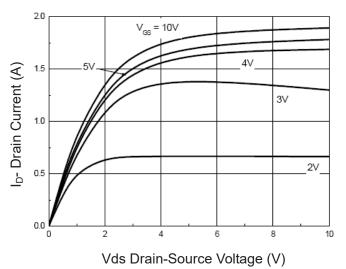


Figure 3 Output Characteristics

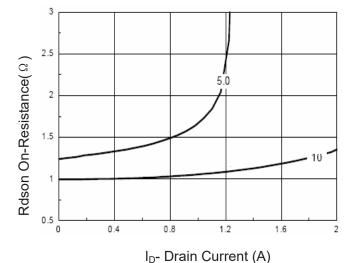


Figure 5 Drain-Source On-Resistance

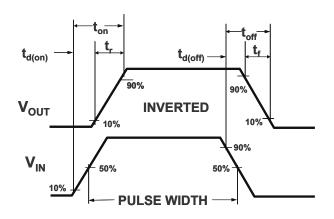


Figure 2:Switching Waveforms

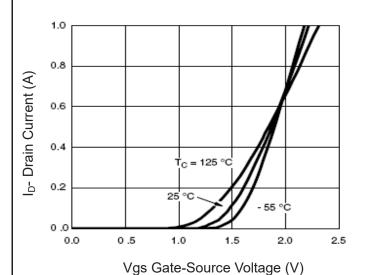
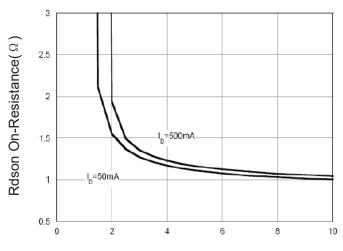


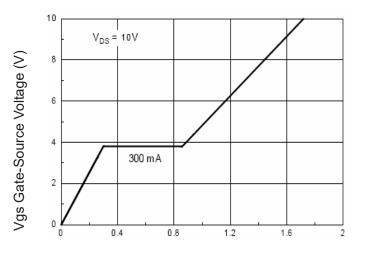
Figure 4 Transfer Characteristics



Vgs Gate-Source Voltage (V)

Figure 6 Rdson vs Vgs





Qg Gate Charge (nC) Figure 7 Gate Charge

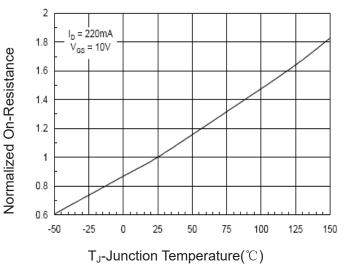


Figure 9 Drain-Source On-Resistance

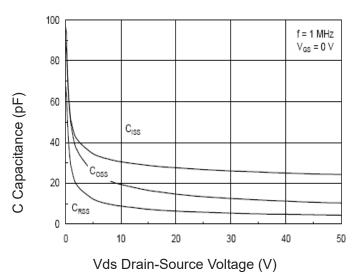
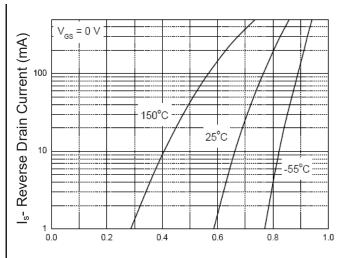
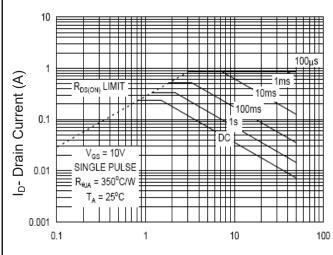


Figure 11 Capacitance vs Vds



Vds Source-Drain Voltage (V)

Figure 8 Source-DrainDiode Forward



Vds Drain-Source Voltage (V)

Figure 10 Safe Operation Area



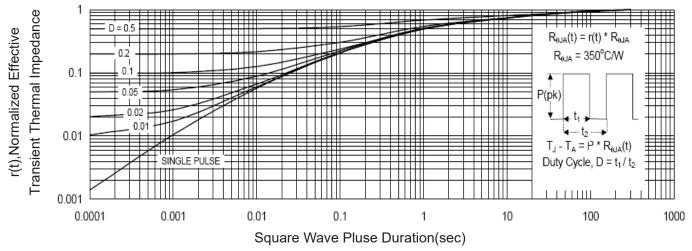


Figure 12 Normalized Maximum Transient Thermal Impedance